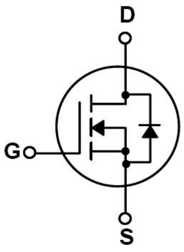
/ Descriptions

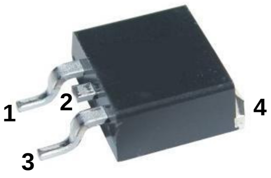
/ Features

/ Applications

/ Equivalent Circuit

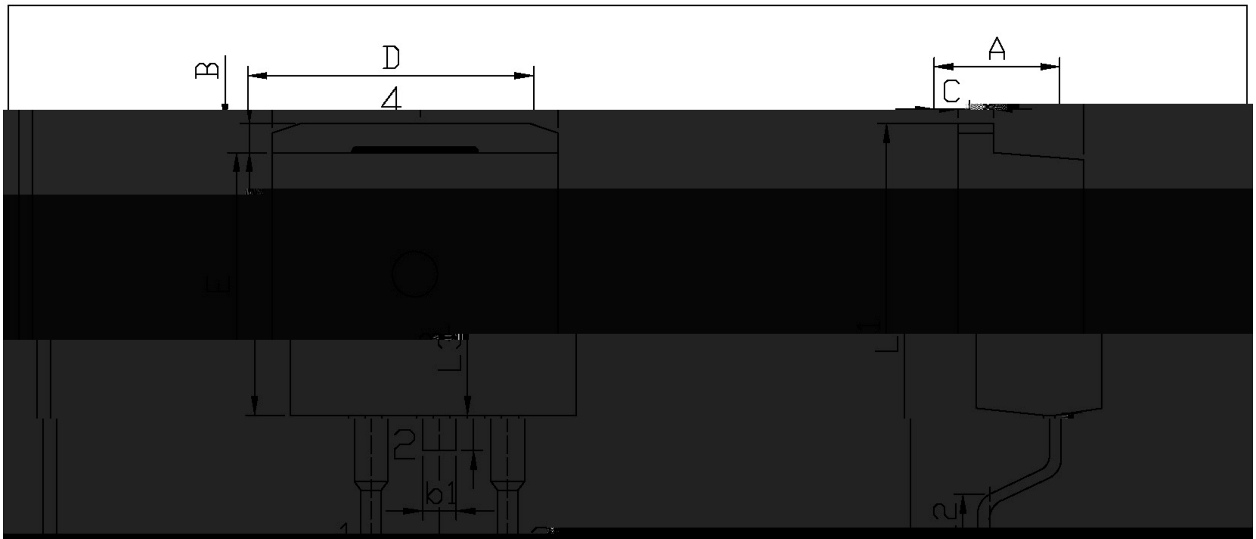


/ Pinning



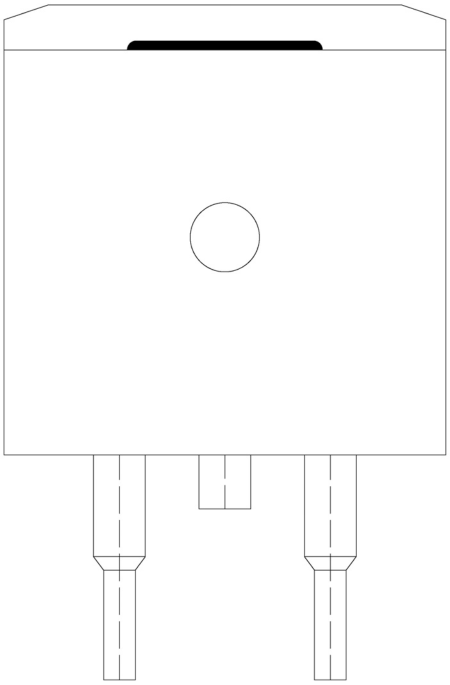
/ h_{FE} Classifications & Marking

/ Package Dimensions

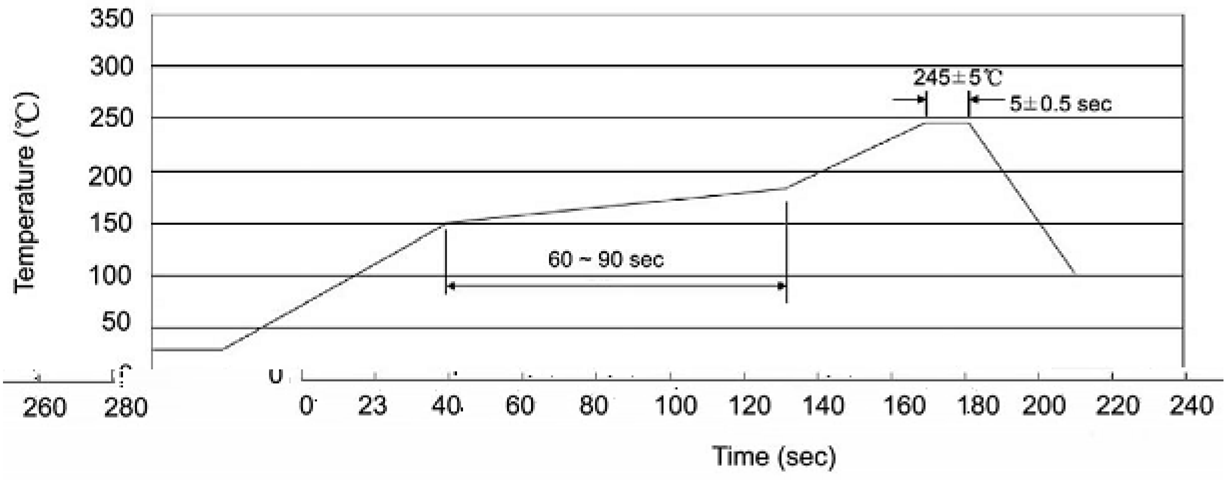


[redacted]

/ Marking Instructions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

℃

/ Packaging SPEC.

封装形式	包装数量					包装尺寸 :		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱